

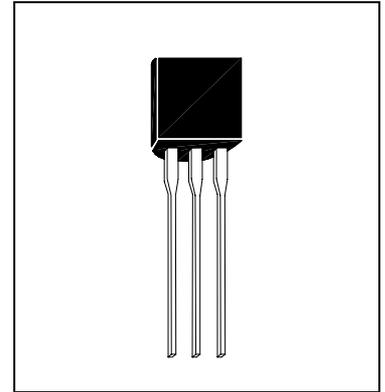


HSB562

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HSB562 is designed for general purpose low frequency power amplifier applications.



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 900 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -25 V
VCEO Collector to Emitter Voltage -20 V
VEBO Emitter to Base Voltage -5 V
IC Collector Current -1 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-25	-	-	V	IC=-10uA, IE=0
BVCEO	-20	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-1	uA	VCB=-20V, IE=0
*VCE(sat)	-	-	-500	mV	IC=-800mA, IB=-80mA
VBE(on)	-	-	-1	V	IC=-500mA, VCE=-2V
*hFE	85	-	240		VCE=-2V, IC=-500mA
fT	-	350	-	MHz	VCE=-2V, IC=-500mA
Cob	-	38	-	pF	VCB=-10V, f=1MHz

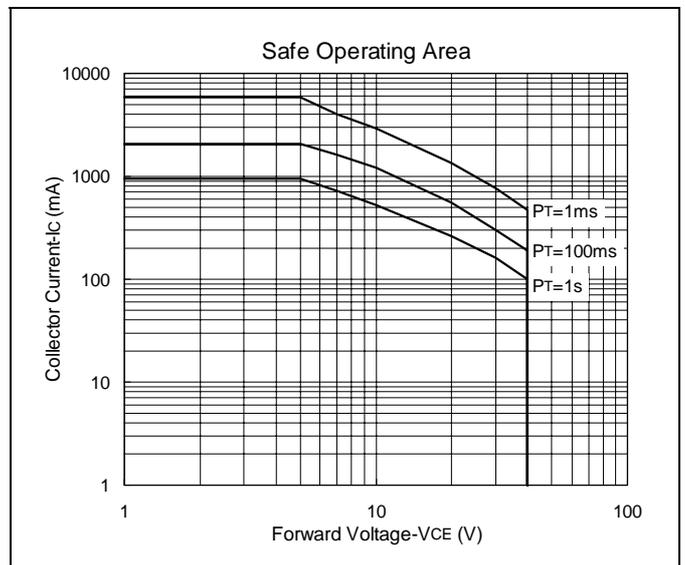
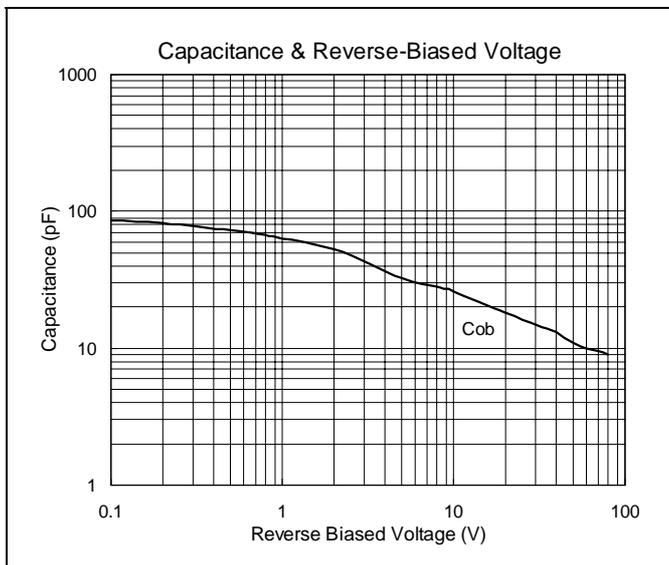
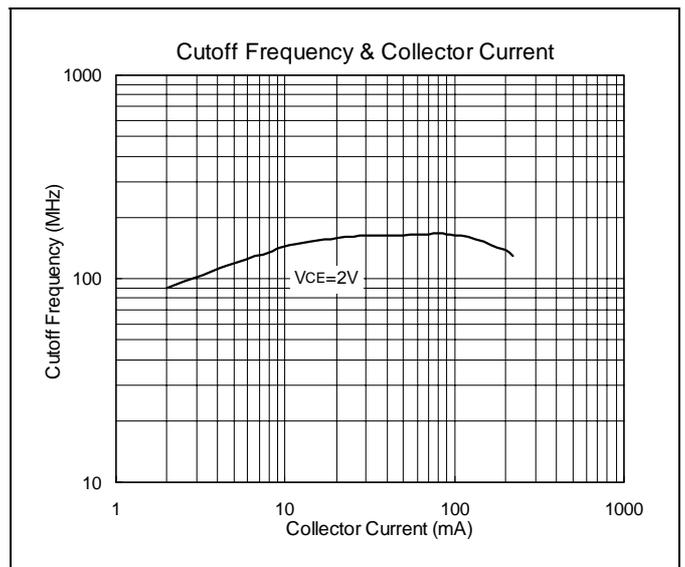
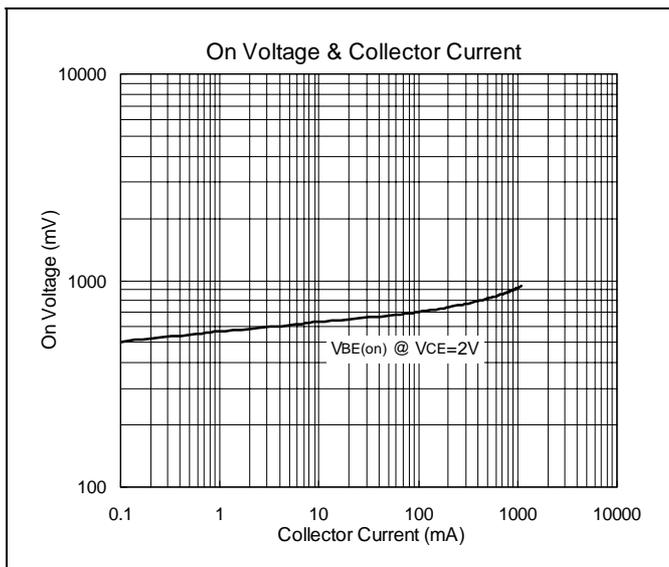
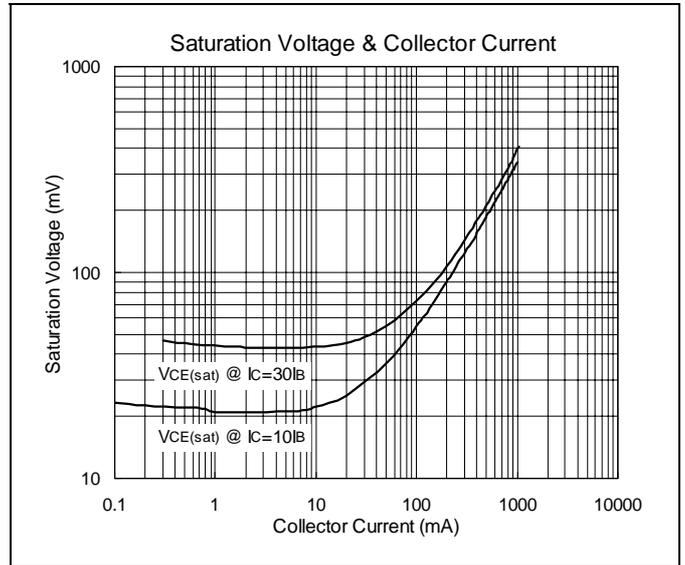
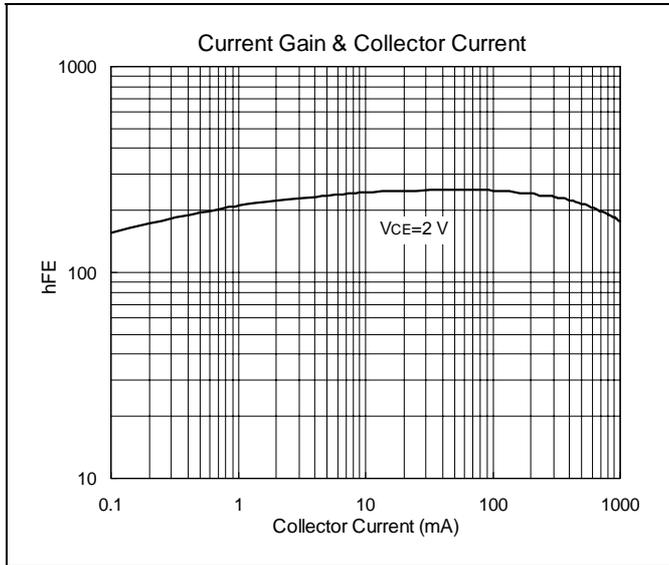
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

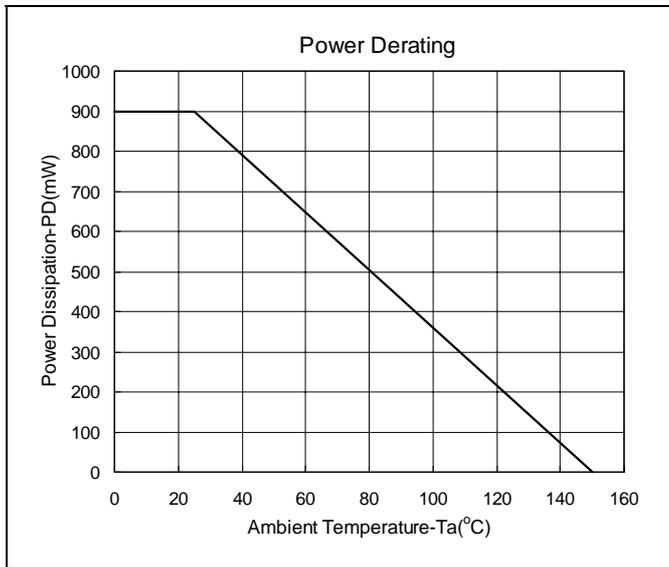
Classification Of hFE

Rank	B	C
Range	85-170	120-240



Characteristics Curve







TO-92 Dimension

3-Lead TO-92 Plastic Package
 HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1. Emitter 2. Collector 3. Base

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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